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April 18, 2003

DUPLICATE  
COPYTo: Examiner Michael Luhrs  
USPTO  
Art Unit 2824  
FAX: 703-746-7473

From: George Simion

Your Ref.: 09/843,924

Our Ref.: 109182

Number of Pages Sent (Including cover sheet): 6

Prepared By: gps

**Comments:**

Examiner Luhrs,

I have enclosed a copy of the Second Supplemental Amendment filed in the USPTO today, April 18.

Please call if you have any questions regarding the Second Supplemental Amendment.

Thank you.

George Simion

Sent by: 

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**PATENT APPLICATION****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of

Kazunori SAKURAI et al.

Group Art Unit: 2824

Application No.: 09/843,924

Examiner: Michael K. Luhrs

Filed: April 30, 2001

Docket No.: 109182

For: METHOD FOR FORMING BUMP, SEMICONDUCTOR DEVICE AND METHOD  
FOR MAKING THE SAME, CIRCUIT BOARD, AND ELECTRONIC DEVICE

**SECOND SUPPLEMENTAL AMENDMENT**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

As supplement to the Supplemental Amendment filed April 11, 2003, please further  
amend the above-identified application as follows:

**IN THE CLAIMS:**

Please replace claim 1:

1. (Twice Amended) A method for forming a bump, comprising:  
forming a resist layer that defines a through hole which overlaps at least a  
portion of a pad;  
forming an opening in an insulating film after forming the resist layer, the  
opening exposing at least a part of the pad; and  
forming a metal layer constituting a bump after forming the opening, the metal  
layer connected to the portion of the pad exposed at the opening.